

**REMARKS**

The following remarks are submitted as a full and complete response to the outstanding Action. By this Amendment, claims 13-15 have been amended for further set forth the application. No new matter has been introduced. Currently, claims 1-41 are pending with claims 1-12, 16-25 and 29-41 withdrawn from consideration. Therefore, claims 13-15 and 26-28 are submitted for reconsideration.

**Acknowledgment**

It is noted that Applicants' election pursuant to a restriction requirement has been acknowledged in items 1-3 of the outstanding Action.

It is also noted that acknowledgment with respect to Applicants' claim for foreign priority and receipt of priority documents has been made in item 4 of the outstanding Action.

**Claim Rejections**

**Claims 13-15 are rejected under 35 U.S.C. §102(e) as being anticipated by *Suyama* (U.S. Patent No. 6,403,463).**

According to the multi-chip semiconductor apparatus as now set forth in claims 13-15, one of the first and second chips is overlaid onto the other so that the circuit surfaces of the first and second chips confront each other. The electrodes on the circuit components of the first chip and the electrodes on the circuit components of the second chip are easily interconnected by the conductive lines (the large-size bus) on one of the first and second chips. The conductive lines (the large-size bus) of the claimed invention

are remarkably shorter than those of the conventional multi-chip semiconductor apparatus discussed in the Applicants' specification.

The large-size bus connection of the invention has a small parasitic capacity and enables the operation at a low driving voltage. A high speed operation of the multi-chip semiconductor apparatus is allowed. The multi-chip semiconductor apparatus of the invention does not require the I/O devices that are needed to connect together the first chip and the second chip as in the conventional multi-chip semiconductor apparatus discussed in the Applicants' specification. Therefore, the delay time is shortened and the power consumption is reduced.

**Suyama** discloses a multi-chip semiconductor apparatus including a plurality of LSI chips. However, in the **Suyama** apparatus, the chips are arranged side by side with the circuit surfaces of all the chips facing upward. The thin-film wiring layer is disposed to cover the entire substrate so that the circuit components are interconnected by the conductive lines of the wiring layer.

**Suyama** specifically does not disclose or suggest a feature of the claimed invention regarding the first and second chips that are disposed such that the circuit surfaces of the first and second chips confront each other. Since the chips are arranged side by side in the **Suyama** apparatus, the total length of the conductive lines to interconnect the circuit components of the chips is relatively long, thereby raising parasitic capacity. Accordingly, it is respectfully submitted that the subject matter of the amended claims 13-15 is neither disclosed nor suggested by **Suyama**.

**Claims 26-28 are rejected under 35 U.S.C. §103(a) as being unpatentable over *Suyama* in view of King et al. (U.S. Patent No. 6,429,528, hereinafter "*King*").**

*King* discloses a multi-chip semiconductor apparatus including a plurality of LSI chips. However, in the *King* apparatus, the semiconductor chips are arranged side by side. The circuit components of the chips are connected by the wire bonding. The conductive leads are disposed across the semiconductor chips and extended to the edges for external connection.

Accordingly, *King* does not supplement for the deficiencies of *Suyama*. Since claims 26-28 depend from amended claim 13, it is respectfully submitted that the subject matter of claims 26-28 is also not rendered obvious by the combination of *Suyama* and *King*.

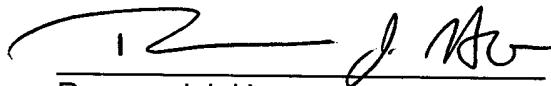
In view of the above remarks, it is respectfully requested that the Examiner reconsiders the application in view of the above arguments, and withdraws the rejections from the application. Particularly, since each of claims 13-15 and 26-28 recites subject matter which is neither disclosed nor suggested in the cited art, it is respectfully requested that each of claims 13-15 and 26-28 is allowable, and this application is passed to issue.

If for any reason the Examiner determines that the application is not now in condition for allowance, it is respectfully requested that the Examiner contact, by telephone, the Applicants' undersigned attorney at the indicated telephone number to arrange for an interview to expedite the disposition of this application.

In the event this paper is not timely filed, the Applicants respectfully petition for an appropriate extension of time. Any fees for such an extension together with any additional fees may be charged to Counsel's Deposit Account No. 01-2300.

Respectfully submitted,

Arent Fox Kintner Plotkin & Kahn, PLLC

A handwritten signature in black ink, appearing to read 'Raymond J. Ho', is written over a horizontal line.

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